

# How machine learning will revolutionize 6G system designs

Devices, air interface and network operations

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6G

Wireless

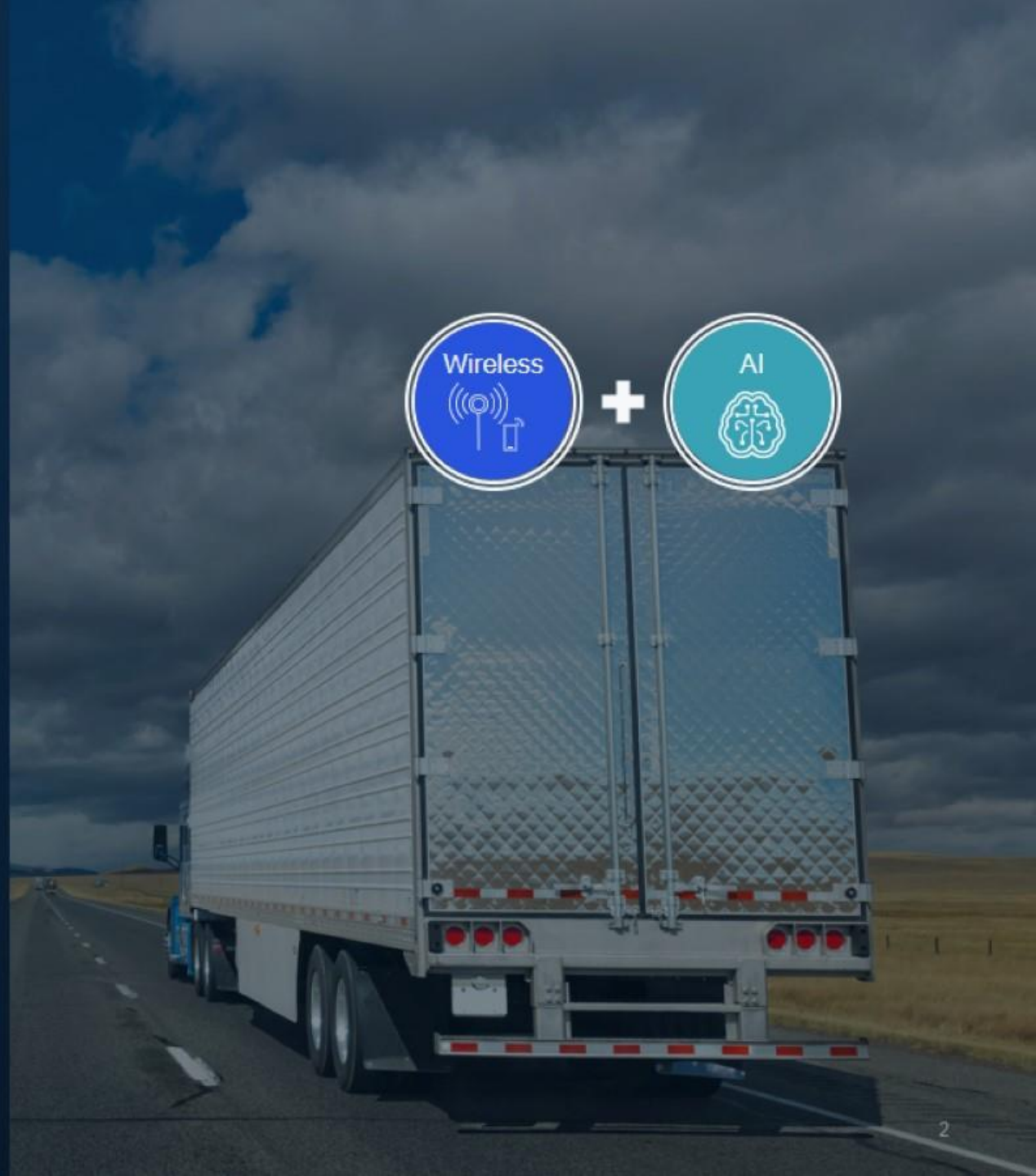


AI

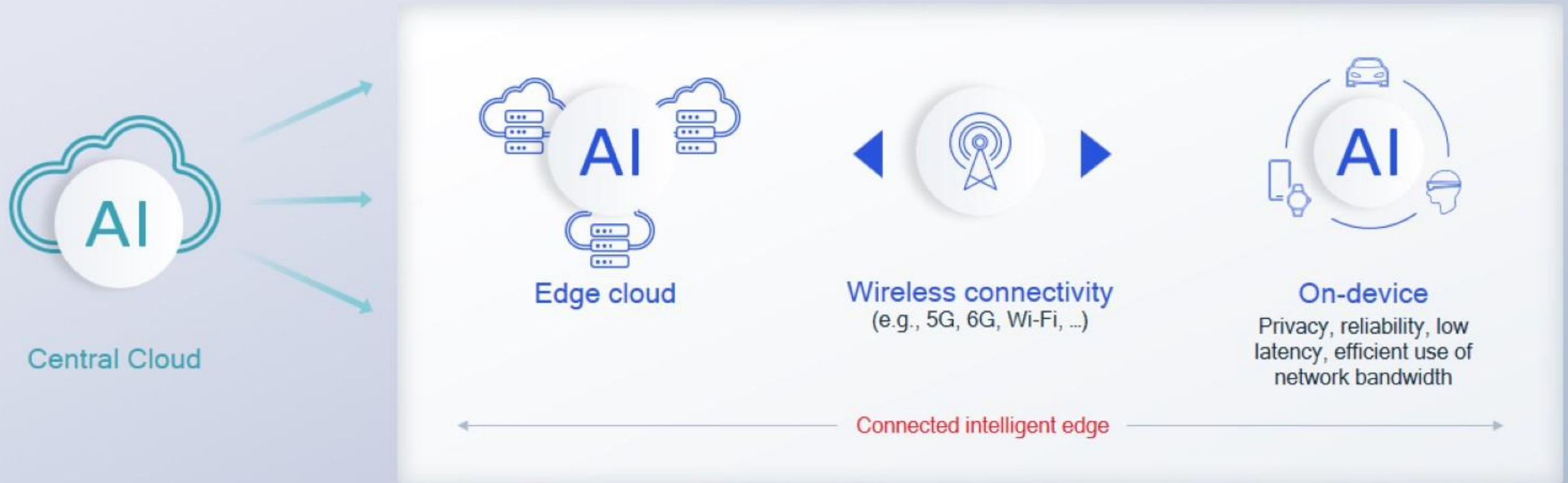


# Today's agenda

- 1 AI enablement of 5G wireless today
- 2 AI-based air interface for 5G-Advanced
- 3 AI for 6G



# To scale efficiently, AI processing is expanding towards the edge



Qualcomm is leading the realization of the **connected intelligent edge**

## CONVERGENCE OF:

Wireless connectivity  
Efficient computing

Distributed AI  
Unleashing massive amount of data to fuel our digital future



# Snapdragon

## X80 5G Modem-RF



AI-enhanced 5G  
Advanced user experience



Multi-antenna management to improve user experience



Contextually-aware QoS and latency improvements



60%\* faster CPE service acquisition (mmWave)



10%\* lower power in connected mode (mmWave)



Location accuracy improvement by 30%\*



Best-cell selection time reduced by 20%\*



30%\* faster link acquisition



Best-in-class performance vs. x86

Up to		Up to
<b>2X</b>	Qualcomm Oryon™ CPU 12 high-performance cores Dual-Core Boost	<b>2X</b>
faster CPU		faster GPU
		Qualcomm® Adreno™ GPU 4.6 teraflops Triple UHD monitor support

**4nm**  
process node

**136GB/s**  
memory bandwidth  
LPDDR5x

Generative AI powerhouse

Capable to run **13B+** parameters on device

Generates **30** tokens/sec for 7B LLMs

Built for AI

**75** TOPS Qualcomm® AI Engine

**45** TOPS Qualcomm® Hexagon™ NPU

**<1 seconds** Stable Diffusion

**4.5X** faster AI NPU processing power than competitors

1st PC processor with integrated Always-Sensing ISP

Integrated Micro NPU on Qualcomm Sensing Hub

Smart user experiences

- Lightning-fast 5G | Wi-Fi 7
- Immersive lossless audio
- Advanced camera ISP
- Snapdragon Seamless
- Chip-to-cloud security

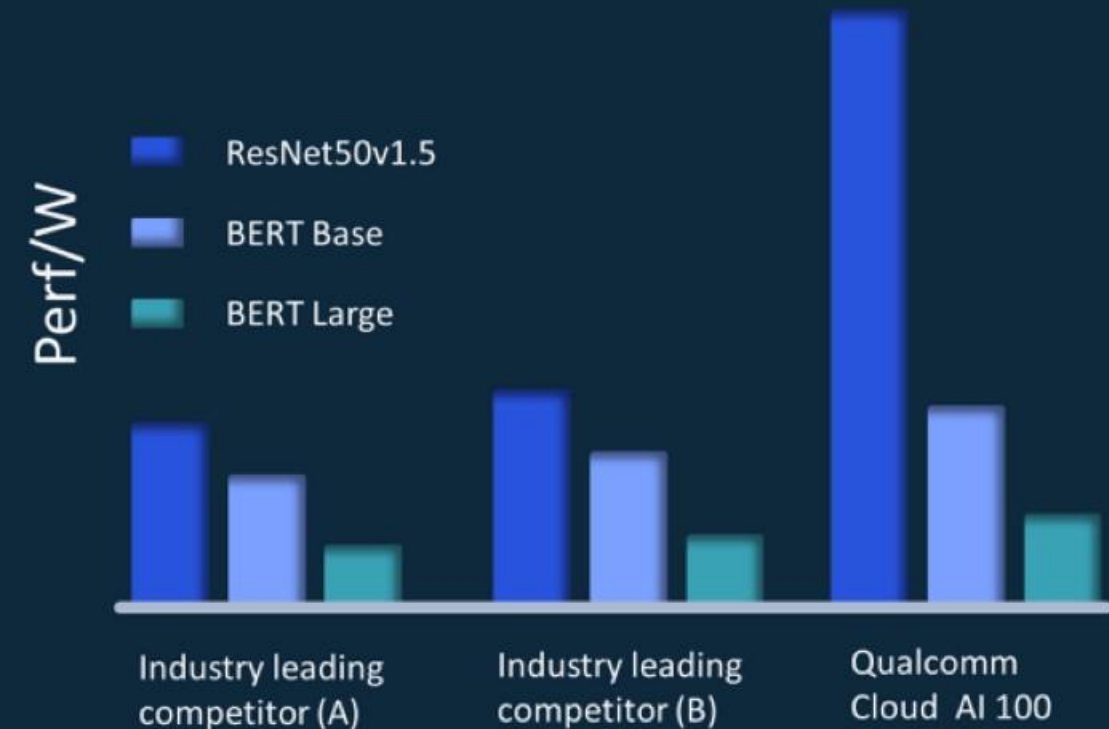
Leading PC performance per watt

Matches peak PC performance at **68%** less power vs. competition

Scalable across a range of thermal designs and form factors

Qualcomm, Snapdragon, Qualcomm Oryon, Adreno, Hexagon, Snapdragon Smart, Snapdragon Sound and Snapdragon Seamless are trademarks or registered trademarks of Qualcomm Incorporated. | CPU Performance is based on Geekbench v6.2 Multi-Thread on Windows OS run in October 2023. Snapdragon X Elite was tested using a Qualcomm laptop reference design on Windows OS. The i7-1380P (12 core) and i7-1355U (10 core) were tested using a Samsung Galaxy Book3 540 (17", 2021) (M2700P) laptop and Samsung Galaxy Book3 13.6" (2021) (NP700P) laptop, respectively on Windows 11. Maximum performance reflected by i7-1380P and i7-1355U represent maximum achievable results in given platforms under unconstrained P1/P2 settings and no thermal limitations. Power and performance comparison reflects results based on measurements and hardware instrumentation of given devices. GPU Performance is based on 3DMark Wildfire Extreme run in October 2023. Snapdragon X Elite was tested using a Qualcomm laptop reference design on Windows OS and a pre-commercial build of Wildfire Extreme. The i7-13800H (14 core) was tested using a Razer Blade 15 2021 (R209-0485) laptop on Windows 11. Maximum performance reflected by i7-13800H represents maximum achievable results in given platform under unconstrained P1/P2 settings and no thermal limitations. Power and performance comparison reflects results based on measurements and hardware instrumentation of given devices.

# Building high performance, power efficient, AI inference accelerator Qualcomm® Cloud AI 100

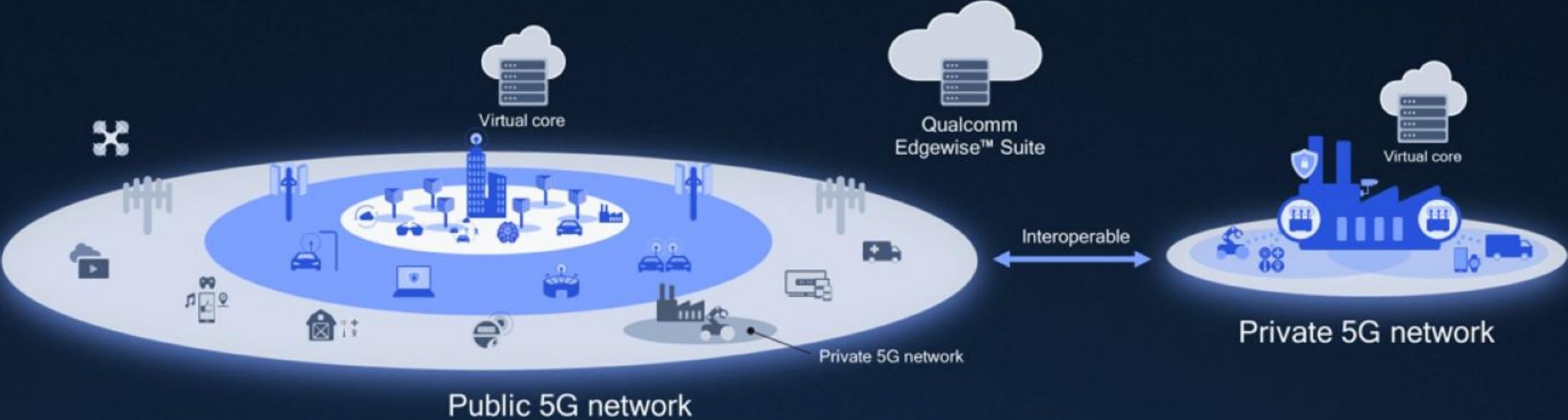


$$\text{Perf/TCO\$} = \text{Inf/sec} / (\text{CapEx} + \text{OpEx})$$

e.g., 4x Perf at same OpEx delivers up to 5x Perf/TCO\$ benefit

Qualcomm solution's 2-4x Performance advantage at similar power leads to 2-5x Perf/TCO\$ advantage

# Qualcomm 5G RAN platforms



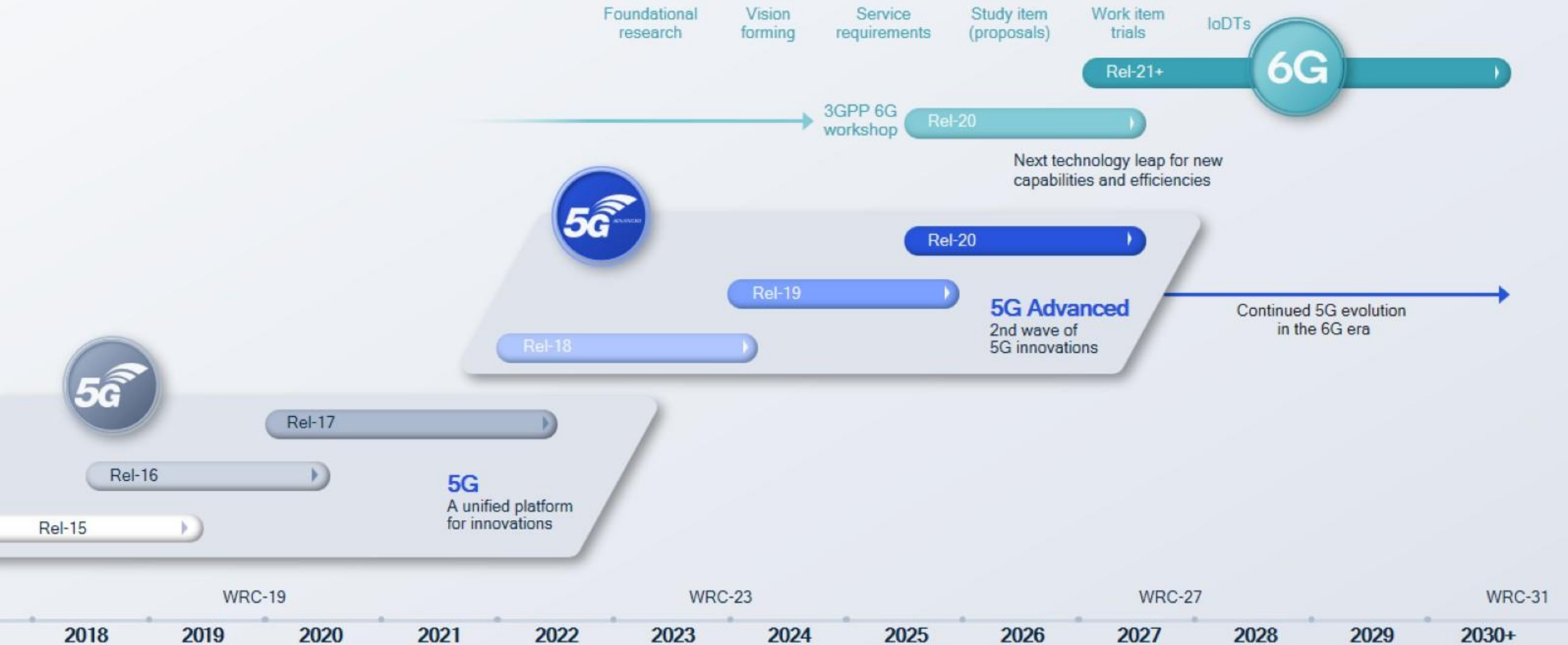
Qualcomm®  
5G RAN  
Platforms



Qualcomm®  
X100 5G RAN  
Accelerator Card



# 5G NR AI-based air interface design in Rel-18+





A KEY PILLAR OF THE  
5G ADVANCED ERA

# Wireless AI

3 projects in Release 19

## Study on AI/ML for Next-Gen Radio Access Network<sup>1</sup>

New use cases including network slicing and coverage and capacity optimization (CCO)

Continued studies on mobility optimization for NR-DC, split architecture support, enhanced energy saving, continuous MDT, and multi-hop device trajectory

## Study on AI/ML to enhance 5G NR mobility<sup>2</sup>

Focusing on L3 device mobility, including RRM measurement & event prediction, device assistance information for network-side model, enhanced LCM, evaluation on testability, interoperability, impacts on RRM requirements and performance

1 RAN 3 led; 2 RAN 2 led; 3 RAN 1 led; 4 Continued study with corresponding checkpoints in RAN#105 (Sept '24)

Source: RP-234039 (AI/ML for NR air interface); RP-234054 (Study on AI/ML for NG-RAN); RP-234055 (Study on AI/ML for mobility in NR)

# Work on AI/ML Air Interface<sup>3</sup>

## General Wireless AI Framework

Support Life Cycle Management (LCM) of one-sided (i.e., device or network) AI/ML models

### Channel feedback<sup>4</sup>

Further study 2-sided CSI compression, 1-sided CSI prediction, model transfer/deliver, ...

Improve user downlink throughput and reduce uplink overhead



### Beam management

Support device/network-sided beam prediction model in time/spatial domain

Reduce overhead, latency, and improve beam selection accuracy



### Precise positioning

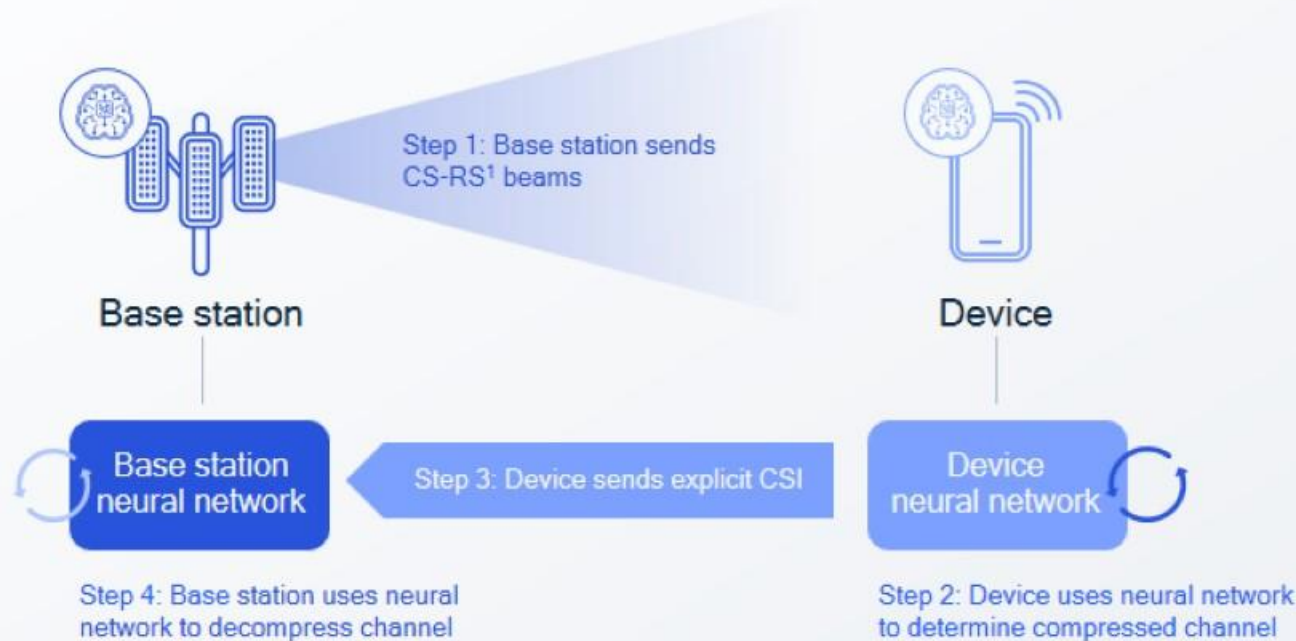
Support single-sided model for both AI-direct and AI-assisted positioning

Improve positioning accuracy for different indoor/outdoor scenarios



# Cross-node machine learning based channel state information

Explicit channel feedback framework for CSI compression and prediction utilizing domain knowledge and neural networks



Improve system efficiency with neural network framework for CSI on non-linear encoding and decoding

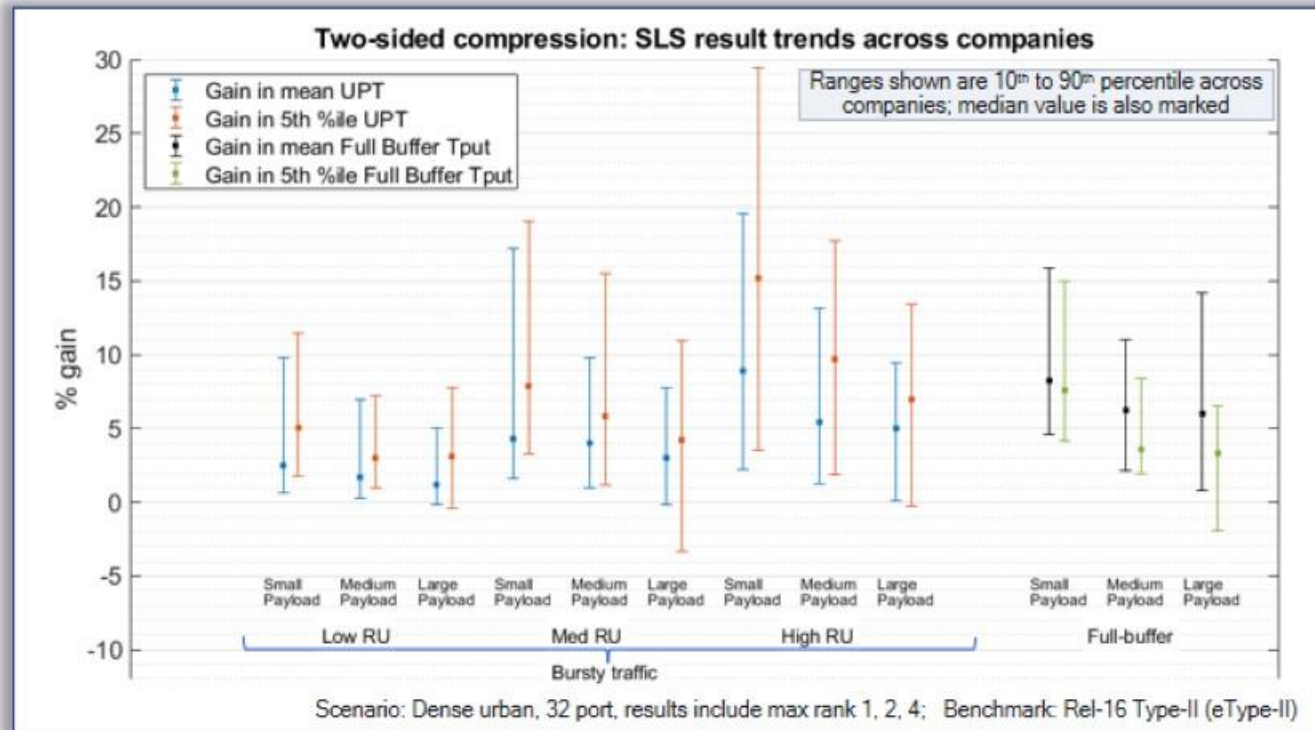
More effective multi-user multiplexing minimizing interference

Customized, lower overhead feedback based on individual device

# Performance gains from 3gpp spatio-frequency CSI compression study

System-level results: Mean and 5<sup>th</sup> %ile Throughput

Assumptions: 3gpp Dense Urban scenarios, 4GHz, 32 CSI-RS ports, 4 Rx, 20MHz comparing ML CSF and eType 2



- CSI feedback overhead reduction: 30-70% reduction in feedback overhead
- Throughput gains: up to 20-30% gain in median and tail user perceived throughput
  - Gains are more pronounced for smaller payload, higher resource utilization, and larger cells.

## Ongoing and future directions

- CSI prediction
- Spatial-frequency-temporal compression
- Joint CSI prediction and compression
- Hyperlocal models
- Joint CSI-RS optimization, feedback, and precoder
- Joint source channel coding on CSI
- Utilizing DL/UL reciprocity for CSI



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# Wireless AI Interoperability For multi-vendor system

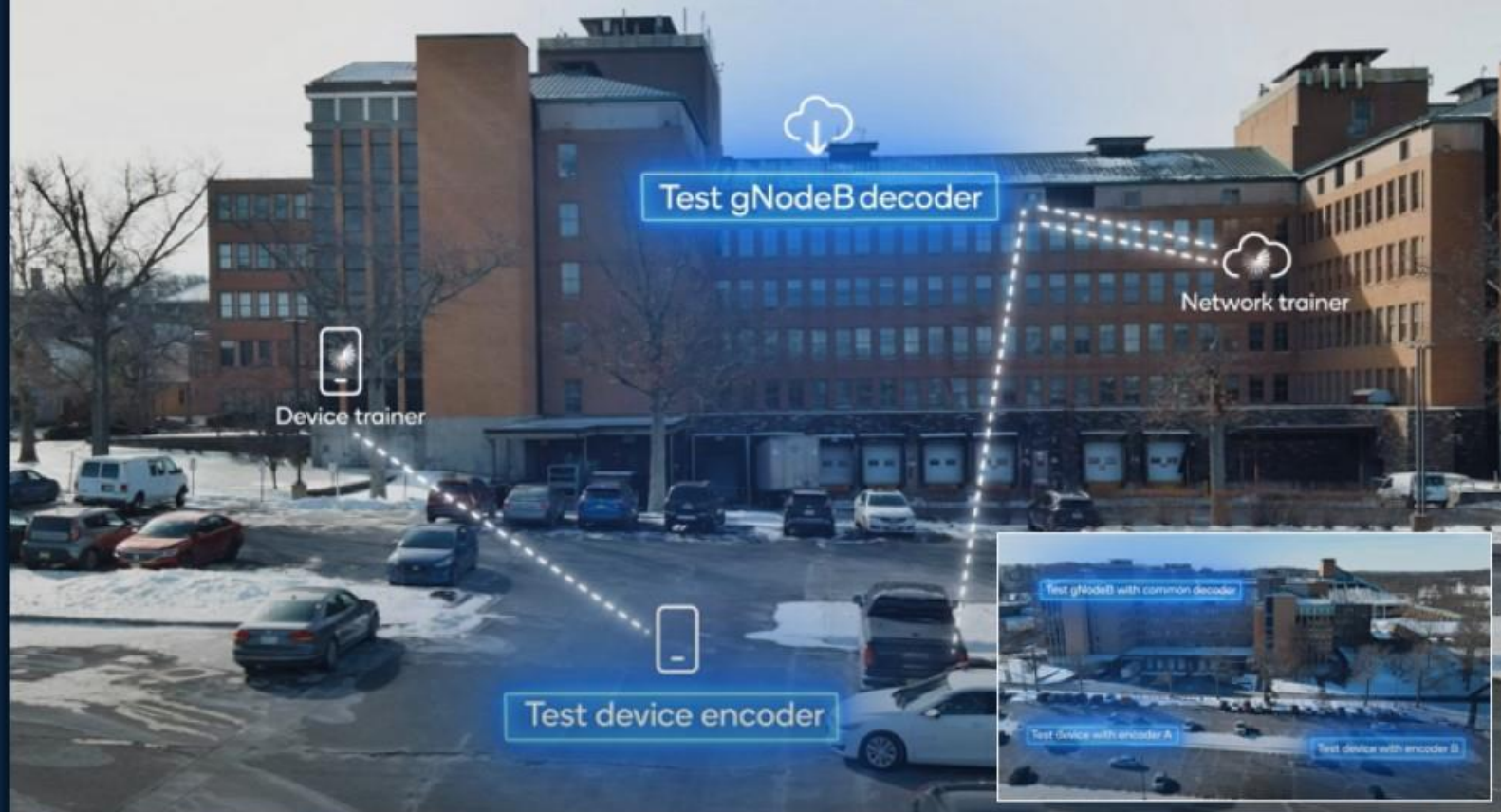
Close collaboration with Nokia Bell Labs on an over-the-air prototype of two-sided channel state information (CSI) feedback

Test network in Murray Hill, NJ, with Nokia infra and Snapdragon 5G Modem-RF

Sequential training enables data sharing but not neural network structures (models)

3GPP global standards compliant, potentially a part of 5G Advanced Rel-19+

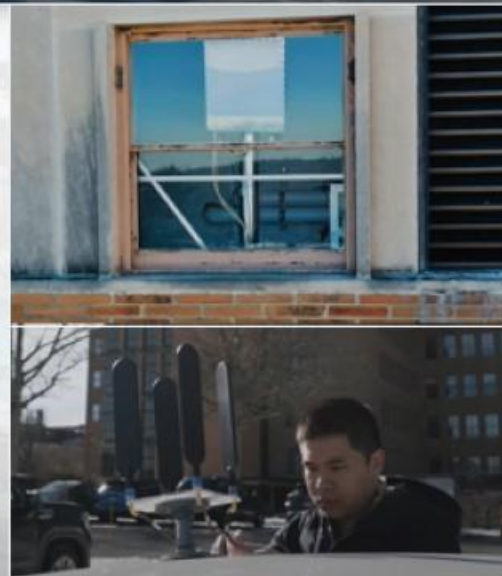
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Downlink throughput - device with encoders



Using a common decoder across all devices performs as well as utilizing a dedicated decoder trained individually for each device





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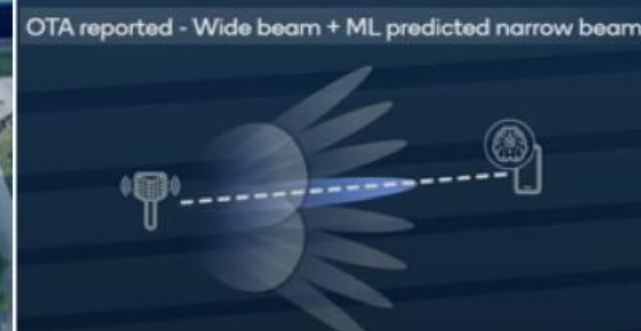
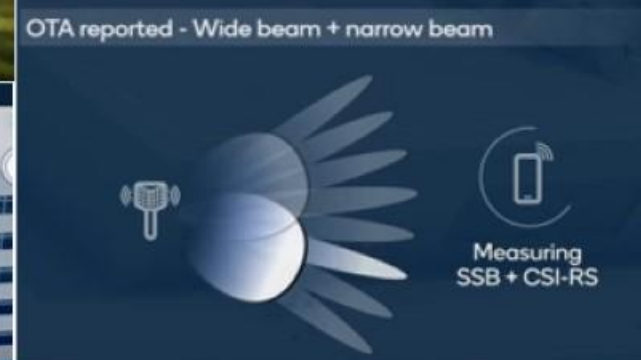
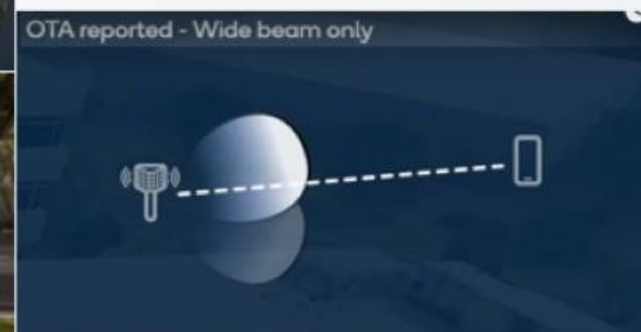
# AI-enabled 5G mmWave Beam Management

Time-domain and spatial-domain device  
beam prediction

Reduced signaling overhead yields a more  
energy-efficient system design

Global standards-compliant design based  
on 3GPP Rel-18/19 projects

Over-the-air testbed operating in the 28  
GHz band with up to 800 MHz bandwidth



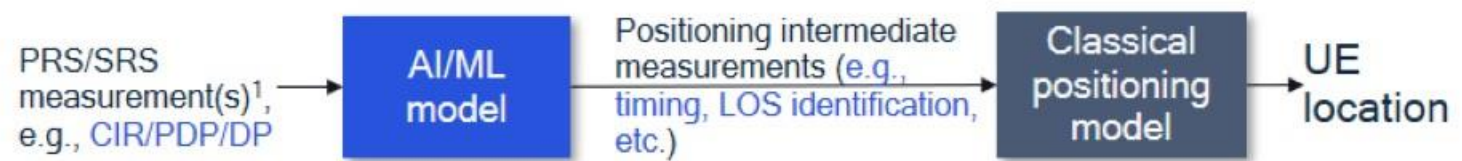
# Performance gains from 3gpp positioning study

AI/ML learns multipath and enhances positioning in challenging NLOS scenarios, reducing positioning error from >10 meters to submeter level

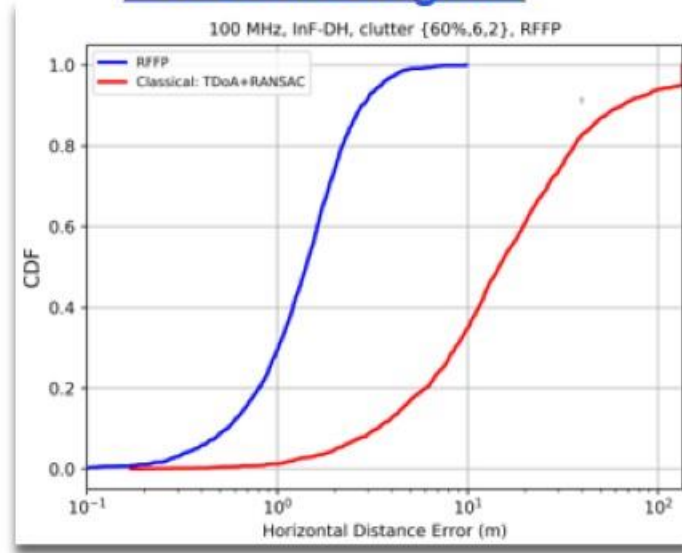
## Direct AI/ML positioning



## AI/ML assisted positioning

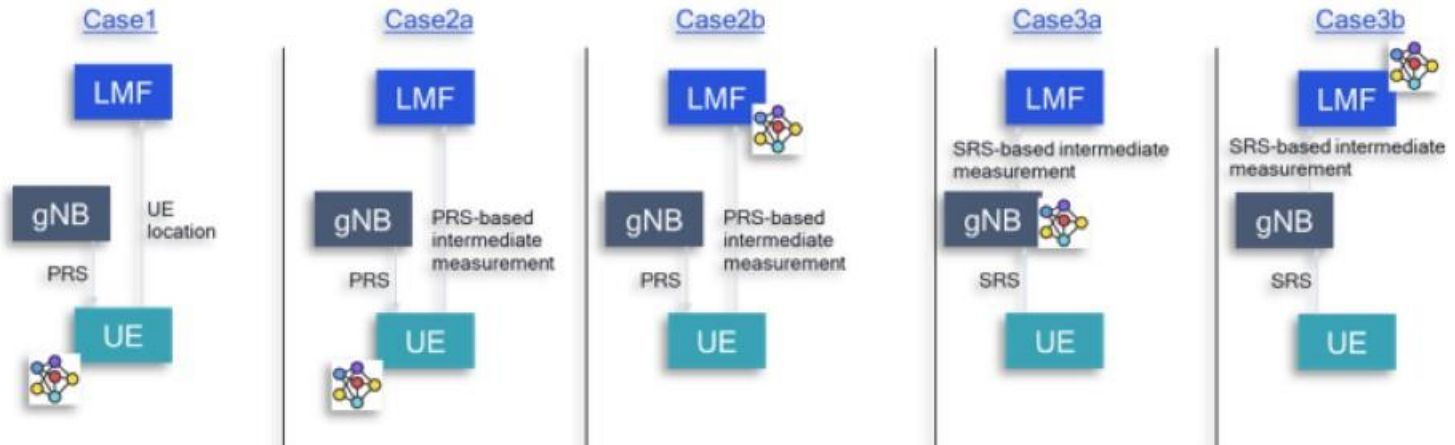


## Performance gains



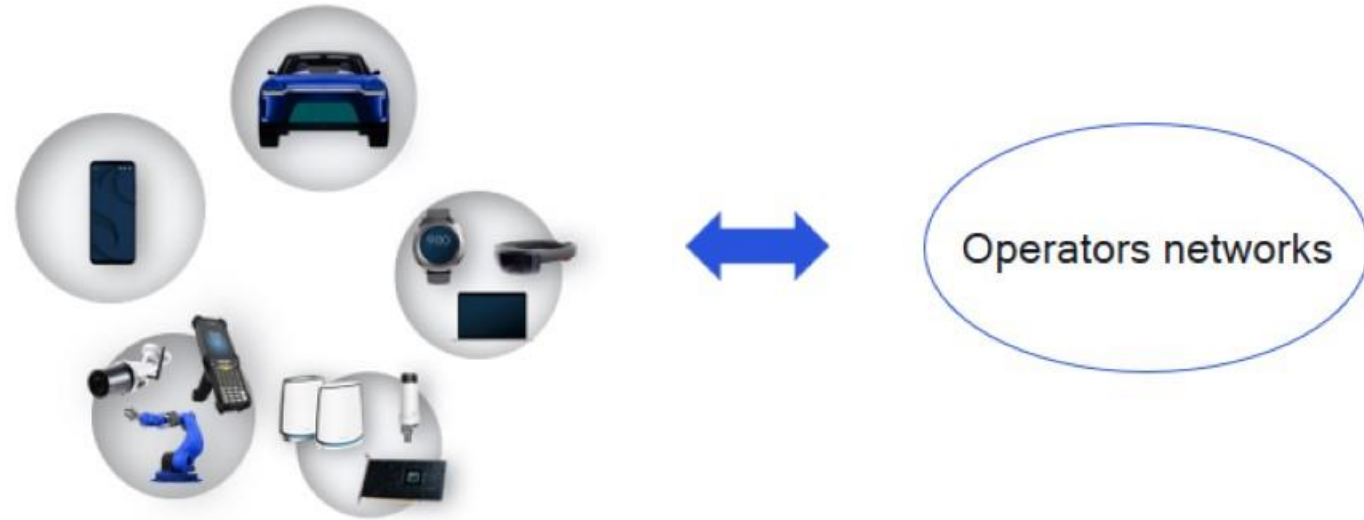
RFFP: direct AI/ML positioning | Extreme NLOS condition (LOS < 1%) | 3GPP InF-DH scenario | Classical: Time difference of arrival with outlier rejection using RANSAC algorithm

## Deployment cases



Note 1: CIR: Channel impulse response | PDP: Power delay profile | DP: Delay profile

# Fundamental 6G motivation



- Increasing revenue with new use cases/services

- Reducing network TCO (total cost of ownership)

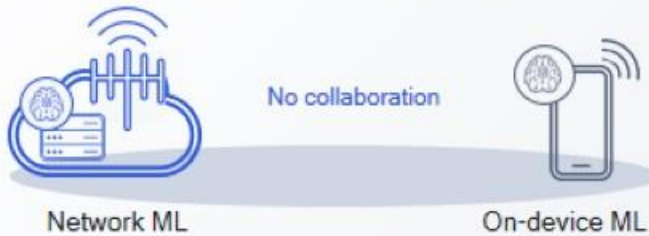


# Evolving towards an AI-native wireless system

## Multiple wireless AI/ML training and inference scenarios

### Overlay AI/ML

INDEPENDENTLY AT THE DEVICE OR NETWORK



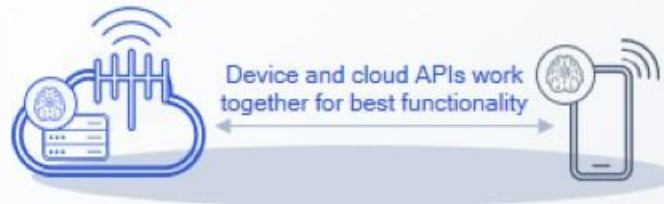
ML operates independently at the device and network as an optimization of existing functions

Proprietary ML procedures including model development and management

Proprietary and standardized data collection used as input to training

### Cross-node AI/ML

COORDINATED BETWEEN DEVICE AND NETWORK



ML operates in a coordinated manner between the device and network

Proprietary and standardized ML procedures including model development and management

Further data collection used as input to training as well as monitoring

### Native AI/ML

AT ALL DEVICE AND NETWORK LAYERS



ML operates autonomously between the device and network across all protocols and layers

Integrated ML procedures across to train performance and adapt to different environments

Data fusion for integrated dynamic ML lifecycle management

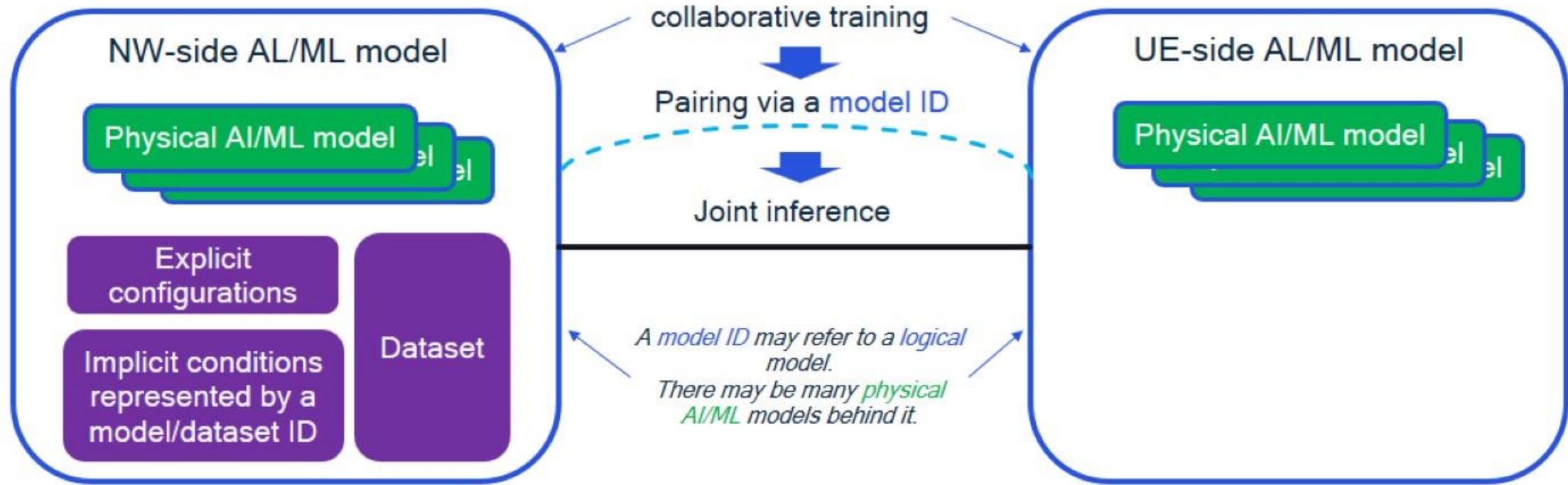
5G

5G  
ADVANCED

6G



# AI-native air interface open issues – Model pairing

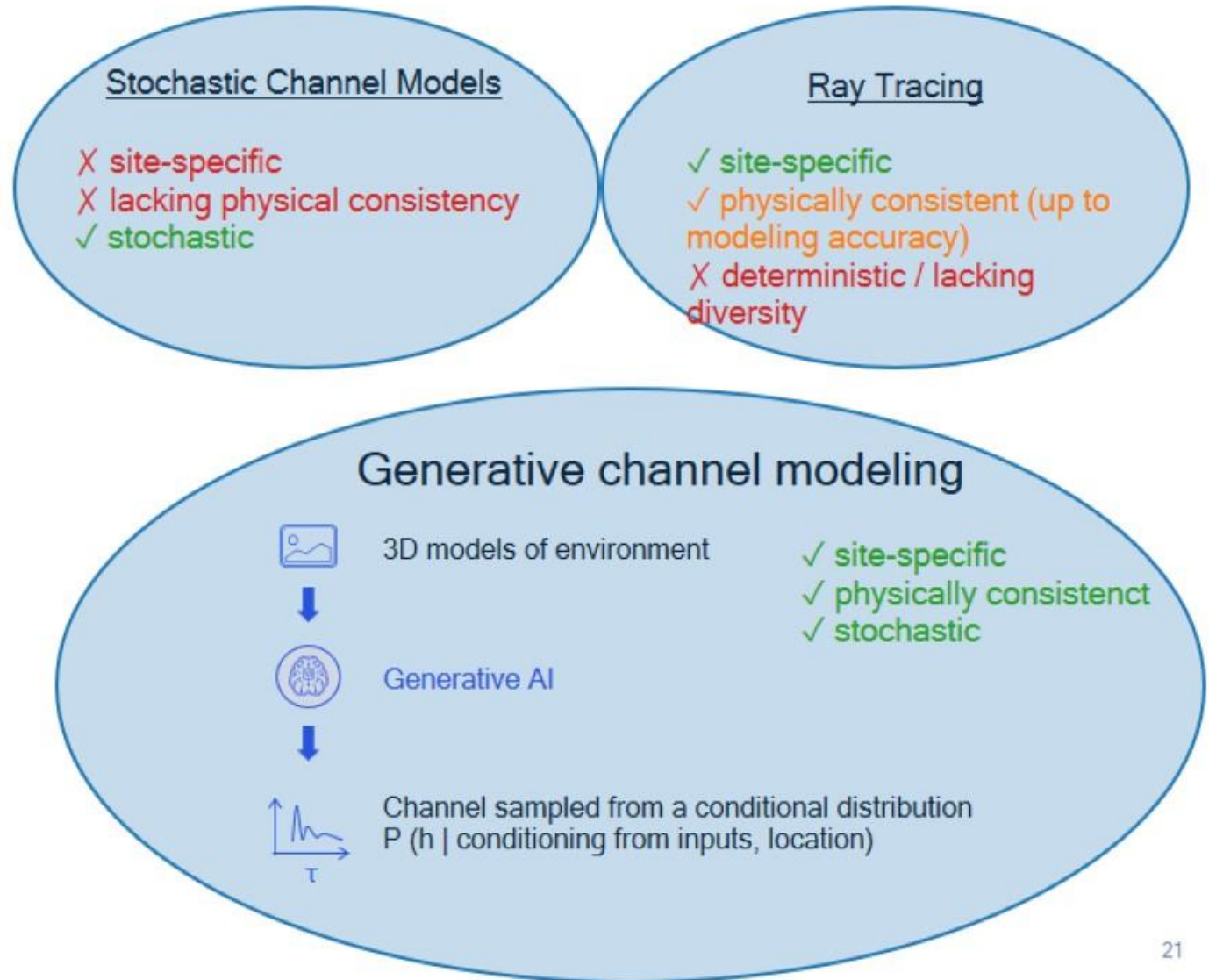


Or there may be no physical AI/ML model at all behind a model ID.

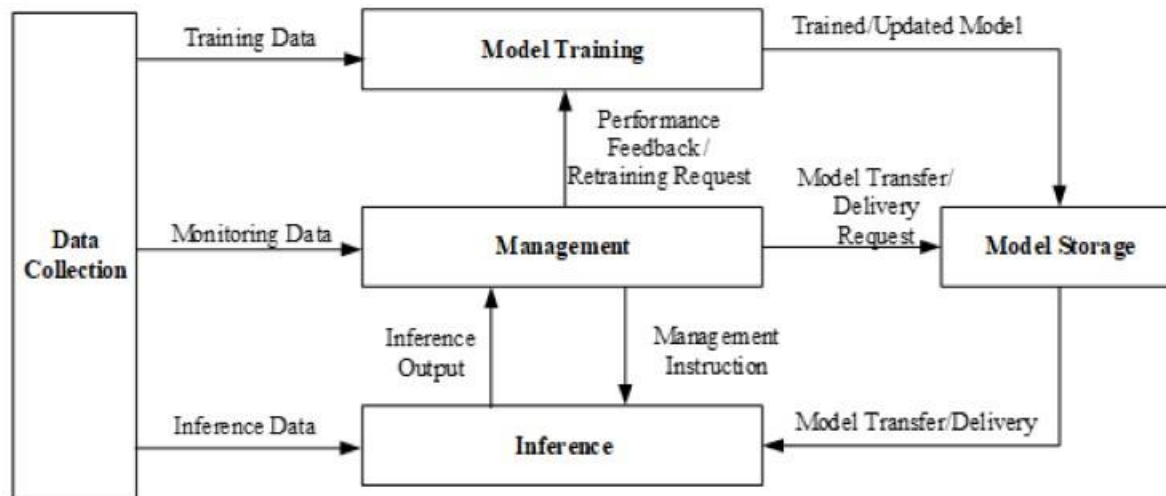
model ID == a set of conditions that determine data distribution, or a dataset itself

# AI-native air interface open issues - channel models

- Conventional communication algorithms have been designed and evaluated based on synthetic channels following stochastic modeling assumptions.
- AI-native air interface design **necessitates new channel modeling framework.**
  - AI/ML models often achieve higher gain when optimized to a given site-specific propagation environment.
  - AI/ML models may not work well in real-world channels when trained on synthetic channels.
  - Channels from Ray Tracing is too deterministic and easily lead to AI/ML model overfitting.
- Data-driven approach may be used toward new channel modeling.

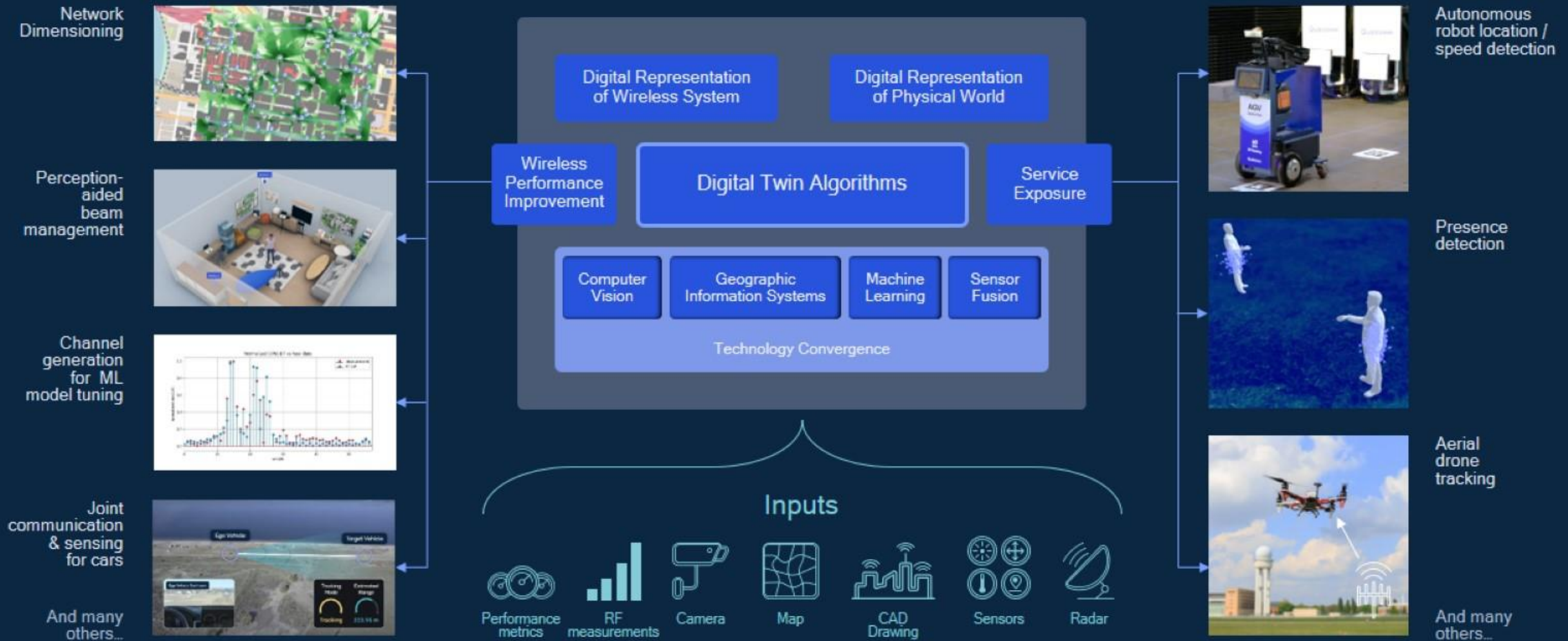


# AI-native air interface open issues - Life cycle management



Source: TR 38.843 v18.0.0, "Study on Artificial Intelligence (AI)/Machine Learning (ML) for NR air interface" (Release 18), December 2023

- Backend ML infra for data collection and model Life Cycle Management (LCM) are important.
- What and how much to specify?
  - Proprietary vs. standardized data collection
  - Proprietary vs. standardized training procedure
  - Proprietary vs. standardized model performance monitoring
- Proprietary innovation vs. standardized interoperability



# Digital Twin - virtual representation of physical system

Monitoring and performance optimization of its real-world counterpart

# Vision for gen AI-augmented and autonomous networks



Intelligent monitoring and management

On-the-fly modeling

Proactive alerts

Programming AI-assistants

'Level-3' autonomous networks



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# Digital Twin Network (DTN)

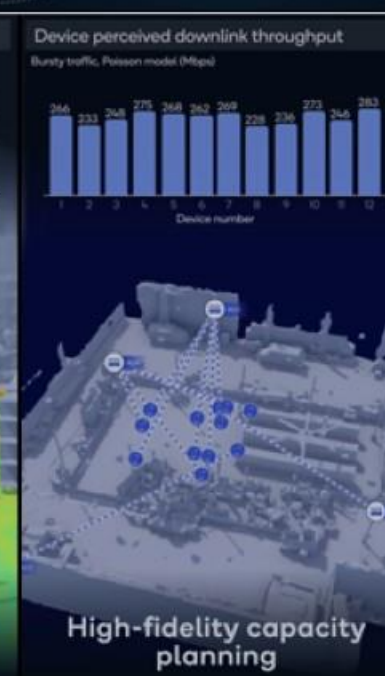
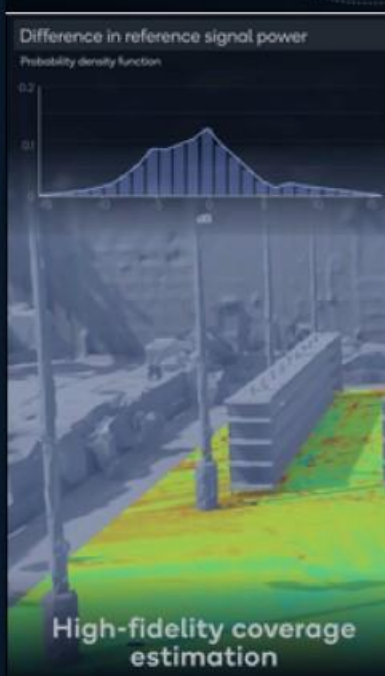
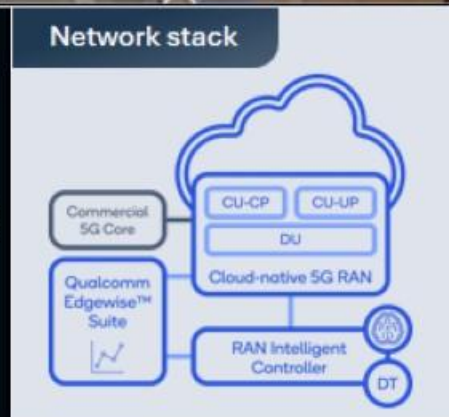
Converging expertise in wireless system modeling, computer vision and AI to create the high-fidelity DTN

Generating synthetic data to address the data collection challenge from real world deployments

Sophisticated dynamic modeling of 5G RAN infrastructure

Over-the-air testbed operating in the 3.35 GHz band with cloud-native 5G RAN, RAN Intelligent Controller (RIC) and the Qualcomm Edgewise™ Suite

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# Applying generative modeling to improve wireless communications system design

## Wide applicability for Generative Modeling



### Real-time use cases for air interface

Propagation channel	Scheduler optimization
Beam management	Traffic source
Interference prediction	Mobility enhancement

Link / system simulation  
Deployment optimization  
Positioning and sensing  
Network and device optimization  
Others...

## Application examples

### Channel rendering



Text description of image or semantic map



Diffusion model  
(To generate channel information)



Channel sampled from a conditional distribution  $P(h | \text{conditioning from inputs, location})$

### Network / device prediction



Context in text, e.g., history of device reports and base station responses



Large language model  
To learn link, beam, protocol languages



Next action for base station and/or device, sampled from a conditional distribution  $P(\text{next action} | \text{conditioning from inputs})$

## Our on-going wireless generative AI research areas

3D mapping and material learning

Foundation models (e.g., link and protocol level use cases, beam prediction, and others)

Neural channel rendering (e.g., map-based, ray tracer augmented, site-specific, and others)

Customized ML-based stochastic channel

Neural surrogate for base station scheduler and applications traffic

And others...

# University Collaborations

## Qualcomm Innovators Development Kit AI/ML and Compute



- Develop AI/ML and compute applications
- Snapdragon® 8 Gen 2 SoC with AI HW/SW

## Snapdragon Spaces™ XR Developer Platform



- Develop immersive AR experiences
- Lenovo Think Reality A3 Glass and Motorola edge+ smartphone kit

## Robotics



- Develop power-efficient robots
- Qualcomm® RB5 Development Kit with Qualcomm® QRB5165 processor (15 TOPS AI, 7 cameras, VSP)
- 5G mezzanine card accessory

Expanding to other platforms in the future

University Courses  
Hackathons

Research projects  
Private-Public projects

Platform Training  
Onboarding Assistance



# Thank you

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